

1. PRODUCT DATA

Type Number 品名编号	Product Model 金属胶带产品	Backing Material 基材	Heat Durability 耐温性(°C)	Thickness of Backing 基材厚度 (mm)	Total Thickness 总厚度 (mm)	Tensile Strength 张力强度	Elongation 伸长率 %	Adhesion Force 粘着力	Adhesive Component 胶体成分	Conductivity 绝缘电阻 (ohms/sg inch)
XPH00252	Copper foil/ Non-conductive Adhesive(单导)	Cu 99.95%	-10 to 120	0.025	0.065	4.8kgf/mm	5-6	0.9kg/25mm	Acrylic	
XPH00352	Copper foil/ Non-conductive Adhesive(单导)	Cu 99.95%	-10 to 120	0.035	0.075	4.8kgf/mm	3-4	0.9kg/25mm	Acrylic	
XPH00502	Copper foil/ Non-conductive Adhesive(单导)	Cu 99.95%	-10 to 120	0.05	0.09	5.2kgf/mm	3-4	0.9kg/25mm	Acrylic	
XPH00253	Copper foil/ Conductive Adhesive(双导)	Cu 99.95%	-10 to 120	0.025	0.065	4.8kgf/mm	5-6	0.8kg/25mm	Conductive Acrylic	0.03-0.06
XPH00353	Copper foil/ Conductive Adhesive(双导)	Cu 99.95%	-10 to 120	0.035	0.075	4.8kgf/mm	3-4	0.8kg/25mm	Conductive Acrylic	0.03-0.06
XPH00503	Copper foil/ Conductive Adhesive(双导)	Cu 99.95%	-10 to 120	0.05	0.09	4.8kgf/mm	3-4	0.8kg/25mm	Conductive Acrylic	0.03-0.06

2. CONSTRUCTURE



Remarks: 1. Total thickness is not included of releasing paper(总厚度以不包含离型纸为标准)

2. 本表为金属箔导电的选码指南, 并需配合各工程单位实际测量数值为准。

3. 测试方式与数值依客户所要求的 ASTM D1000 所得出。

4. The data is subject to change without notice.

5. 绝缘电阻值单指胶的部分, 而非整个产品, 该数值会因铜, 铝或其它基材不同有所改变。

3. Adhesion Analysis

*本测试条件为常温 25°C, 相对湿度 65°C 底下采用美国 ASTM-D1000 所得之结果

胶性	热感压性亚克力胶混合型接着
溶剂	醋酸 ^o 酯 ^o 苯
粘度	(BROOKFIELD LVE NO.4 @25°C) 9000±1000 CPS
固形份	(150°C*15Min) 40±1%
导电份子	Silver, Nickel, Cu
初期粘着力	(J.DOW METHOD) 1.0kg/25mm †
保持粘着力	(PSTC-7) 1440 Min/inch †
耐温性	-10°C~120°C
绝缘电阻	0.03~0.06 ohms/sg inch

4. OTHERS APPLICATION:

OUR EMI SOLUTION PRODUCT CAN BE APPLIED TO THE FCC, CE STANDARD MONITOR, DESKTOP PC, NOTEBOOK PC, CABLE ASSEMBLY AND COMMUNICATION DEVICES.

ADVANTAGES: (BY PINHAN ELECTRONIC)

ESCELLENT HEAT RESISTANCE

PERFECT SHIELDING EFFECTIVENESS WITH SMOOTH APPEARANCE

AVAILABLE SPECIAL SHAPE AND CUSTOMER REQUEST SPECIFICATION

铜箔胶带对于电磁波干扰屏蔽有良好效果, 对于接地后静电泄放有良好表现, 铜箔胶带还可以用于焊锡用途。